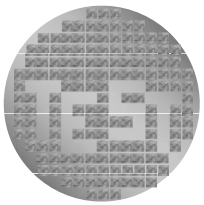


VLSI Design

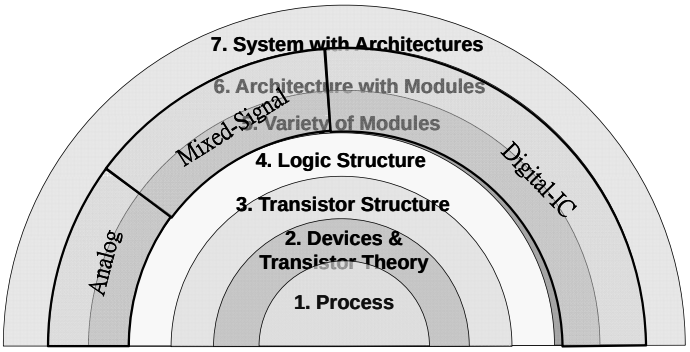
Tsung-Chu Huang

Department of Electronic Engineering
National Changhua University of Education
Email: tch@cc.ncue.edu.tw

2016/02/23

Syllabus Structure

Bottom-up Hierarchy



Notes

Before Class

- Question and Answer in English
  - ✓ Ask a question in English about last lesson.
- 10-minute Quiz
  - ✓ Answer a 10-minute quiz
  - ✓ Evaluate and correct by each other
  - ✓ Try to answer in English

MOS Transistor Theory

Basic Semiconductor Devices in MOS Process

- Resistance
  - ✓ Metal, Silicide, Poly, Diffusion, Well, Chanel
- Coil Inductor
  - ✓ Spiral Metal
- Plate Capacitor
  - ✓ Metal Poly, Poly-Poly, Poly-Substrate, Chanel
- MOS Transistor
  - ✓ V-I Characteristics/Modeling
  - ✓ Pass Transistor Operation
  - ✓ Chanel Resistance
  - ✓ Gate Capacitance
  - ✓ Transistor Diode
  - ✓ Pass Transistor and Switch

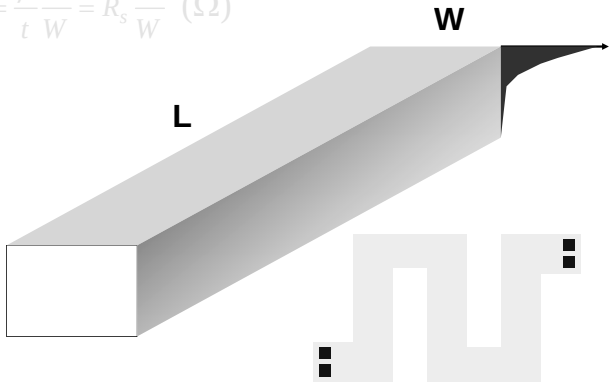
MOS Transistor Theory

Usual Semiconductor Elements in MOS Process

- Wire Resistance
  - ✓ Metal, Silicide, Poly, Diffusion, Well, Chanel
- Coil Inductor
  - ✓ Spiral Metal
- Plate Capacitor
  - ✓ Metal Poly, Poly-Poly, Poly-Substrate, Chanel
- MOS Transistor
  - ✓ V-I Characteristics/Modeling
  - ✓ Pass Transistor Operation
  - ✓ Chanel Resistance
  - ✓ Gate Capacitance
  - ✓ Transistor Diode
  - ✓ Pass Transistor and Switch

Sheet Resistance

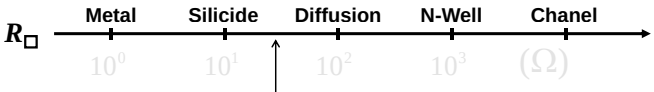
$$R = \frac{\rho}{t}\frac{L}{W} = R_s \frac{L}{W} \quad (\Omega)$$



e.g., Polysilicon resistor, diffusion resistor

Wire Sheet Resistance

- Approximate Orders in about 2000's Technologies:



- Resolution: **Polysilicon ➔ about 1% error**
  - ✓ **Polysilicon is usually the best wire sheet resistor for accurate resistance.**
- Heat Radiation: In a 5-face adiabatic model,

$$H \propto A = WL$$

MOS Transistor Theory

Basic Semiconductor Devices in MOS Process

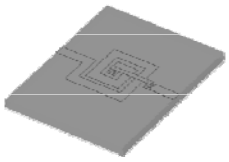
- Resistance
  - ✓ Metal, Silicide, Poly, Diffusion, Well, Chanel
- Coil Inductor
  - ✓ Spiral Metal
- Plate Capacitor
  - ✓ Metal Poly, Poly-Poly, Poly-Substrate, Chanel
- MOS Transistor
  - ✓ V-I Characteristics/Modeling
  - ✓ Pass Transistor Operation
  - ✓ Chanel Resistance
  - ✓ Gate Capacitance
  - ✓ Transistor Diode
  - ✓ Pass Transistor and Switch

Coil Inductor

- **Cylindrical air-core coil:**

$$L = \frac{\mu k N^2 A}{l} \text{ (Henries, H)} \qquad \begin{cases} N: \#\text{turns} \\ A: \text{ Area} \\ l: \text{ length} \end{cases}$$

- **Flat Spiral Inductor:**



MOS Transistor Theory

Basic Semiconductor Devices in MOS Process

- Resistance
  - ✓ Metal, Silicide, Poly, Diffusion, Well, Chanel
- Coil Inductor
  - ✓ Spiral Metal
- Plate Capacitor
  - ✓ Metal Poly, Poly-Poly, Poly-Substrate, Chanel
- MOS Transistor
  - ✓ V-I Characteristics/Modeling
  - ✓ Pass Transistor Operation
  - ✓ Chanel Resistance
  - ✓ Gate Capacitance
  - ✓ Transistor Diode
  - ✓ Pass Transistor and Switch

Plate Capacitance

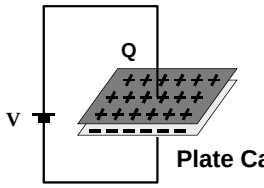
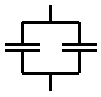
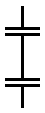


Plate Capacitance: $C \equiv \frac{Q}{V} = \varepsilon \frac{A}{t}$

Permittivity — **Area** / **Thickness**

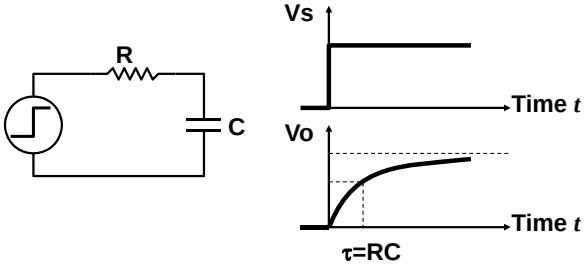


$C = C_1 + C_2$



$$C = \frac{1}{\frac{1}{C_1} + \frac{1}{C}}$$

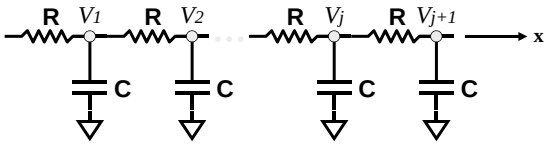
First Order Time Constant



Charging Energy: $\frac{1}{2}CV^2$

Nothing to do with R!

Transmission Line Effect



$$C\frac{dV_j}{dt} = (I_{j-1} - I_j) = \frac{V_{j-1} - V_j}{R} - \frac{V_j - V_{j+1}}{R}$$

$$rc\frac{\delta V}{\delta t} = \frac{\delta^2 V}{\delta x^2}$$, where $$r = \frac{\delta R}{\delta x}$$ and $$c = \frac{\delta C}{\delta x}$$

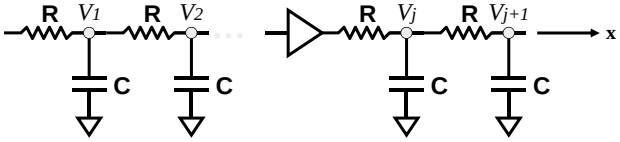
It's a wave function,
and the propagation time for step response:

$$t_x = kx^2$$

Transmission Line Effect

Approximate propagation time: $$t_n = \frac{RCn(n+1)}{2}$$

One solution to reduce the propagation time:
Adding buffers:

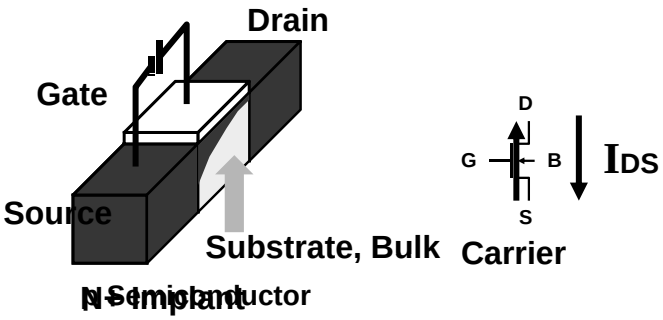


MOS Transistor Theory

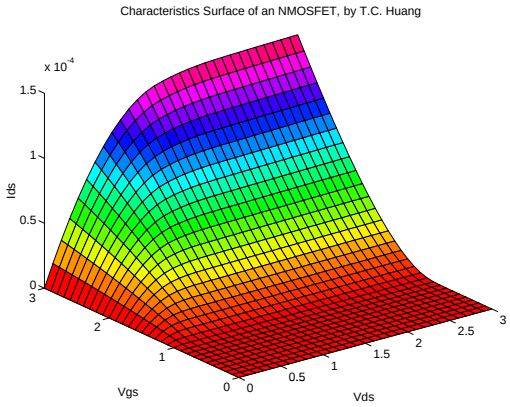
Basic Semiconductor Devices in MOS Process

- Resistance
  - ✓ Metal, Silicide, Poly, Diffusion, Well, Chanel
- Coil Inductor
  - ✓ Spiral Metal
- Plate Capacitor
  - ✓ Metal Poly, Poly-Poly, Poly-Substrate, Chanel
- MOS Transistor
  - ✓ V-I Characteristics/Modeling
  - ✓ Pass Transistor Operation
  - ✓ Chanel Resistance
  - ✓ Gate Capacitance
  - ✓ Transistor Diode
  - ✓ Pass Transistor and Switch

An n-Type MOS Transistor



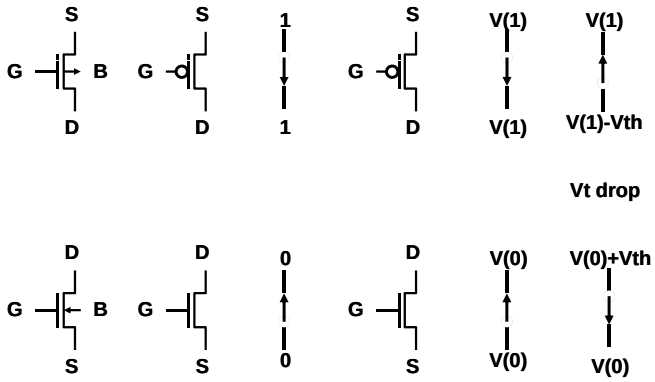
Device Model



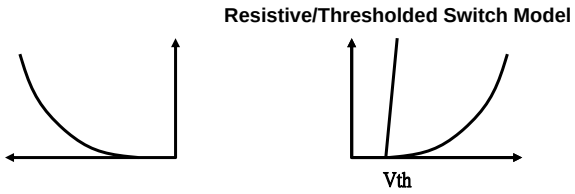
Levelized Power/Timing Models

- ✓ **RTL Level and Models as Heuristics**
  - **Transition count model,**
  - **Imax,**
  - **Charge model as Thermal model, etc.**
- ✓ **Logic Level and Speedup Model**
  - **Switching model,**
  - **RC Model,**
  - **Elmore Model**
- ✓ **Manual Model**
  - **First-order equations**
  - **Lambda Rules for Voltage Scaling**
- ✓ **SPICE Model**
  - **Level 1 (simple dc)**
  - **Level 2 (modified)**
  - **Level 3 (+ Empirical short-channel)**
  - **Level 4 (BSIM)**
- ✓ **Physics and Electronics Levels**
  - **Physics and Electronics Theories, MOS Model, BJT Model, p model**

Switch Intention

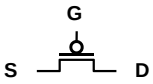


Simple Switch Model of an n-MOSFET

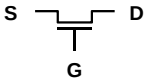


Pass Transistor as Switch

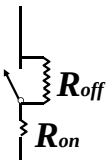
1. Good p/n switch for 1/0 but bad for 0/1
2. CMOS Transmission gate – another compensated structure

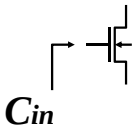


3. Pass Transistor Logic (PTL)
   1. VDD >> stages * Vth
   2. Pulled-up or down

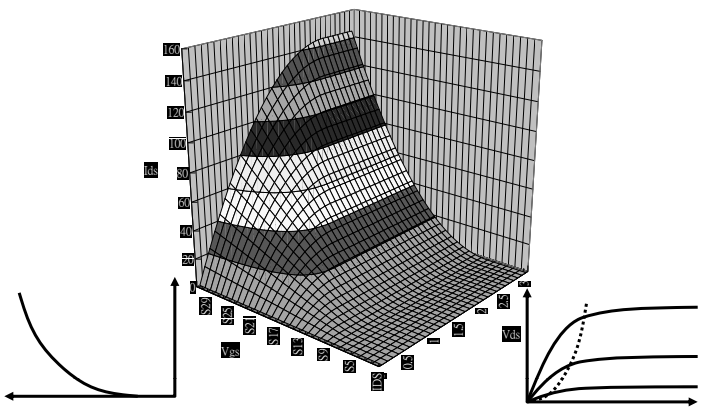


RC Switch Model



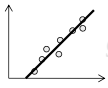


Measured Characteristics of a MOSFET



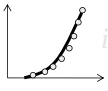
Useful Regressions

- Linear Regression (α=1)
  - ✓ First-Order Equation



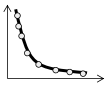
$$g_m = k(v_{gs} - v_t)$$

- Second-Order Regression (α=2)
  - ✓ Parabolic Regression



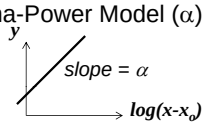
$$i_{ds} = k(v_{gs} - v_t)^2$$

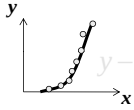
- Hyperbolic Regression (α=-1)



$$R_s(v_{gs} - v_t) = k$$

- Alpha-Power Model (α)



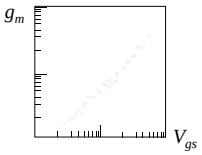


$$y - y_o = (x - x_o)^{\alpha}$$

First-Order Equation

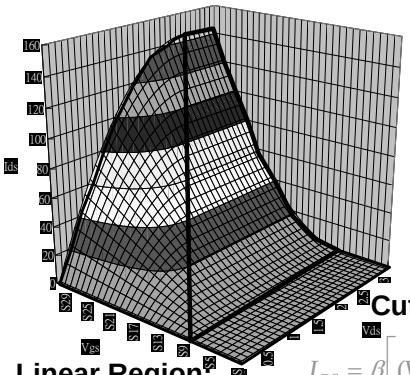
Linear Regressed by Power Law

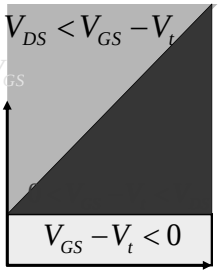
- Bardeen, Shockley and Brattain at Bell Labs, 1948
- Nobel prize in 1956 for inventing transistor
- From previous experimental results:



- First-Order Equation: $g_m \equiv \frac{\partial i_{DS}}{\partial v_{GS}} = \beta(V_{GS} - V_{th})$

First Order (Shocklay) Equations





Cut-Off Region: $I_{DS} = 0$

Linear Region: $I_{DS} = \beta\left[(V_{GS} - V_t)V_{DS} - \frac{V_{DS}^2}{2}\right]$

Saturation Region: $I_{DS} = \frac{\beta}{2}(V_{GS} - V_t)^2$

MOS Transistor Gain Factor β

$\mu_p \approx 200cm^2/(V \cdot \sec)$

$\mu_n \approx 500cm^2/(V \cdot \sec)$

Gate Oxide Capacitance $C_{ox} \equiv \frac{\varepsilon}{t_{ox}}$

$\approx 4\varepsilon_o$

Mobility

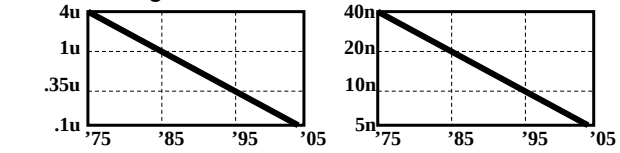
Channel Width

Permittivity

$\beta = K\frac{W}{L} = \frac{\mu\varepsilon}{t_{ox}}\frac{W}{L}$

Channel Length

Oxide Thickness

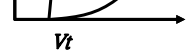


Threshold Voltage

$V_t = V_{t-mos} + V_{fb}$

Flat band voltage

- Gate-Substrate Work Function
- Surface State Charge

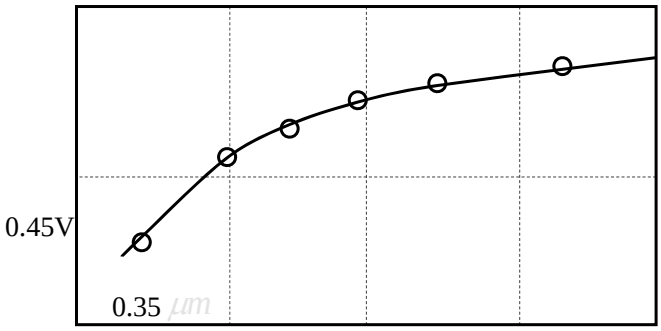


MOS Capacitor Threshold Voltage

- doping
- t_o
- Oxide Capacitance
- Bulk Charge Term

Usually, while the process technology is fixed, VLSI Layout Engineers can only take care of V_B and T (temperature).

Threshold Voltage Changing due to Short Channel



Threshold Voltage Changing due to Bulk Voltage

$|V_t| = |V_{to}| + \Delta V_t$

$\Delta V_t \approx \gamma(\sqrt{2\Phi_F + V_B} - \sqrt{2\Phi_F})$

$\Delta V_t << 2\Phi_F \qquad \Delta V_t \approx \gamma\sqrt{V_B}$

(A Typical value of γ is about 0.6)

Channel Sheet Resistance

- Linear Region: VCR (Voltage Control Resistance) Region.

Linear Region: $I_{DS} = \beta\left[(V_{GS} - V_t)V_{DS} - \frac{V_{DS}^2}{2}\right]$

$$R \equiv \frac{\delta V_{DS}}{\delta I_{DS}} = \frac{1}{\mu C_{ox}(V_{GS} - V_t - V_{DS})} \cdot \frac{L}{W} \approx \frac{1}{\mu C_{ox}(V_{GS} - V_t)} \cdot \frac{L}{W}$$

Channel Sheet Conductance $\sigma_s \approx \mu C_{ox}(V_{GS} - V_t)$

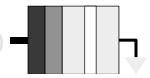
- Approximate Orders in about 2000's Technologies:

$R_{\square}$

Metal	Silicide	Diffusion	N-Well	Chanel
10^0	10^1	10^2	10^3	(Ω)

MOS Capacitance

$V_{GB} > 0$



Depletion

High Frequency

$V_{GB} = 0$

Depletion

Gate Capacitance: $C \equiv \frac{C_{SiO_2} C_{dep}}{C_{SiO_2} + C_{dep}}$

$V_{GB} < 0$

Accumulation

Oxide Capacitance: $C \equiv \frac{\varepsilon_{SiO_2}\varepsilon_o}{t_{ox}} A$

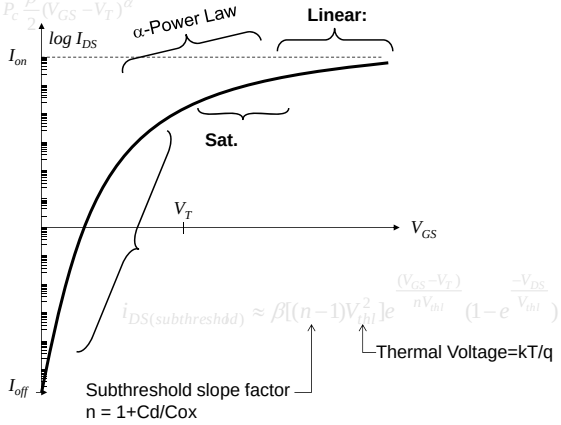
Approximate Intrinsic MOS Gate C□

Cg =

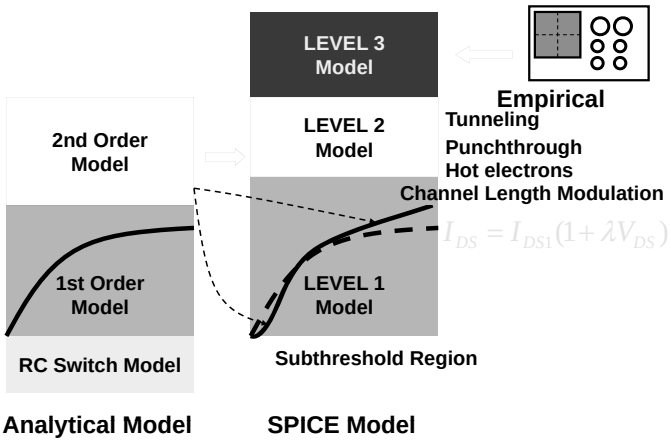
Region / Portion	Cut-off	Linear	Saturated
C_{gb}	$\frac{\varepsilon A}{t_{ox}}$	0	0
C_{gs}	0	$\frac{\varepsilon A}{2t_{ox}}$	$\frac{2\varepsilon A}{3t_{ox}}$
C_{gd}	0	$\frac{\varepsilon A}{2t_{ox}}$	0

Ideal IDS Model considering Subthreshold

$i_{DS} = P_c \frac{\beta}{2}(V_{GS} - V_T)^{\alpha}$



SPICE Modeling



Transistor Power/Timing Models

Summary

- Switch Models
  - ✓ Ideal Switch: Functional simulation without timing
  - ✓ Resistive Switch: Static power evaluation
  - ✓ Capacitive Switch: Dynamic power evaluation
  - ✓ RC Switch: Basic power and timing evaluation
- Transistor Structure Model
  - ✓ El More Model: loop RC additive.
  - ✓ Rabaey Model: Logical and branch efforts
- IDS Models
  - ✓ Shockley First-Order Equation: accurate manual derivation
  - ✓ Sub-threshold Models
- SPICE Models
  - ✓ Complicate Simulation

Transistor Network

Relay Logics

- **Stack Effect**
  - ✓ Parallel Switch: $S_{on} = A_{on} + B_{on}$, $R_s = R_A // R_B$
  - ✓ Serial Switch: $S_{on} = A_{on} \cdot B_{on}$, $R_s = R_A + R_B$
  - ✓ Parallel Capacitors: $C = C_A + C_B$
- **Body Effect**
  - ✓ is the threshold voltage changing of source-bulk voltage due to transistor connection in series.

$$V_{t2} \approx V_{t2} + 0.6\sqrt{V_{D1}}$$